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Kind regards,

Team Nexperia

AN11106

Pin FMEA for AHC/AHCT family

Rev. 1 — 4 November 2011

Application note

Document information

| Info | Content |
|-----------------|--|
| Keywords | FMEA, AHC, AHCT, CMOS |
| Abstract | This application note provides a Failure Modes and Effects Analysis (FMEA) for NXP Semiconductors AHC/AHCT family during typical failure situations. |



Revision history

| Rev | Date | Description |
|------------|-------------|--------------------|
| v.1 | 20111104 | initial version |

Contact information

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1. Introduction

The Advanced High-Speed CMOS (AHC and AHCT) family of logic devices from NXP Semiconductors, offers many of the same functions found in the High-Speed CMOS (HC and HCT) family. However, it has higher performance and lower power consumption than the HC/HCT while maintaining competitive prices. In addition, NXP Semiconductors guarantees AHC/AHCT products to operate over an extended temperature range of $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$. The increase in product specification is at no extra cost to the customer.

The AHC/AHCT family of products is ideally suited for notebooks, telecom infrastructure, and portable applications. The capability to operate at both 5 V and 3.3 V, further extends its integration into new designs. The dual voltage facilitates the migration of existing designs to low-voltage systems and establishes it as a truly mixed-voltage product.

The AHC/AHCT family includes gates, octals, MSI, and 16 bit-wide devices. It is both functionally and pin-for-pin compatible with the HC/HCT family of products.

2. Pin FMEA

This chapter provides an FMEA (Failure Mode and Effect Analysis) for typical failure situations. The failure situations are when the pins of a type in the AHC/AHCT family are shorted to supply voltages V_{CC} , GND or neighboring pins, or simply left open.

The individual failures are classified in accordance with their corresponding effects on the AHC/AHCT device and its functionality (see [Table 1](#)).

Table 1. Classification of failure effects

| Class | Failure effect |
|-------|---|
| A | damage to device affects application functionality |
| B | no damage to device can affect application functionality |
| C | no damage to device no affect to application functionality |

Table 2. FMEA matrix for pin short-circuit to V_{CC}

| Pin | Class | Remarks |
|--------|-------|---|
| Input | B | normal operating condition, no damage, no leakage, can affect functionality |
| Output | C | if output defined HIGH, no damage, no leakage, no output level change |
| Output | A | if output defined LOW, short-circuits and high currents can damage device, output level changes |
| GND | B | short-circuits and high currents can damage device, affects functionality |

Table 3. FMEA matrix for pin short-circuit to GND

| Pin | Class | Remarks |
|-----------------|-------|--|
| Input | B | normal operating condition, no damage, no leakage; can affect functionality |
| Output | C | if output defined LOW, no damage, no leakage no output level change |
| Output | A | if output defined HIGH, short-circuits and high currents can damage device, output level changes |
| V _{CC} | B | no damage, affects functionality |

Table 4. FMEA matrix for pin left open

| Pin | Class | Remarks |
|-----------------|-------|---|
| Input | B | undefined operating condition, no damage, increases leakage, can affect functionality |
| Output | C | normal operating condition, no damage, no leakage |
| GND | B | undefined operating condition, no damage, increases leakage, affects functionality |
| V _{CC} | B | undefined operating condition, no damage, increases leakage (only for I/O types), affects functionality |

Table 5. FMEA matrix for pin short-circuits between neighboring pins

| Pin | Class | Remarks |
|---------------------------|-------|--|
| Input to input | C | if inputs have same voltage levels: no damage, no leakage |
| | B | if inputs have different voltage levels: leakage increases, affects functionality |
| Input to output | A | if input and output have different voltage levels, can cause high current and can damage device, affects functionality |
| | C | if input and output have same voltage levels, no damage, no leakage |
| Input to GND | - | see Table 3 |
| Input to V _{CC} | - | see Table 2 |
| Output to output | C | if outputs have same voltage levels, no damage, no leakage |
| | A | if outputs have different voltage levels, can cause high current and can damage device, affects functionality |
| Output to input | - | same effect as 'input to output' condition |
| Output to GND | - | see Table 3 |
| Output to V _{CC} | - | see Table 2 |
| GND to V _{CC} | - | not applicable, these pins are not neighbors |

3. Abbreviations

Table 6. Abbreviations

| Acronym | Description |
|---------|---|
| AHCT | Advanced High-Speed CMOS TTL |
| CMOS | Complementary Metal-Oxide Semiconductor |
| FMEA | Failure Modes and Effects Analysis |
| LSTTL | Low-power Schottky TTL |
| TTL | Transistor-Transistor Logic |

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